

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---|---|------------------|---------|------------------|
| L1 | 46 | @ad<="20031022" and 'dielectric constant' same 'solder mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/30 15:37 |
| S1 | 722 | @ad<="20031022" and 'PCB' and 'signal trace' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 14:09 |
| S2 | 71 | @ad<="20031022" and 'PCB' and 'signal trace' and 'low impedance' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 08:49 |
| S3 | 140 | @ad<="20031022" and 'differential' with 'signal trace' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 10:59 |
| S4 | 49 | @ad<="20031022" and 'PCB' and 'differential' with 'signal trace' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 09:12 |
| S5 | 1 | "6005895".PN. | USPAT; USOCR | OR | ON | 2005/01/12 08:59 |
| S6 | 1 | "5956518".PN. | USPAT; USOCR | OR | ON | 2005/01/12 09:00 |
| S7 | 7 | @ad<="20031022" and 'copper trace' same 'coupling' same 'dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 09:21 |
| S8 | 70 | @ad<="20031022" and 'copper' with 'high dielectric' same 'low dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 09:42 |
| S9 | 115 | @ad<="20031022" and 'interconnection' and 'copper layer' and 'high dielectric' and 'low dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 09:42 |
| S10 | 13 | @ad<="20031022" and 'differential' with 'signal line' and 'high dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 10:29 |
| S11 | 735 | @ad<="20031022" and (257/664-665).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:17 |

| | | | | | | |
|-----|-----|--|---|----|----|------------------|
| S12 | 585 | @ad<="20031022" and 'differential signal line' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 10:48 |
| S13 | 44 | @ad<="20031022" and 'differential signal trace' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 10:30 |
| S14 | 51 | @ad<="20031022" and 'differential signal line' same 'coupling' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 10:45 |
| S15 | 3 | @ad<="20031022" and 'differential signal line' same 'dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 10:50 |
| S16 | 24 | @ad<="20031022" and 'PCB' and 'differential signal line' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 10:50 |
| S17 | 1 | 'PCB' and 'base layer' and 'ground plane' and 'stripline' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:00 |
| S18 | 356 | 'PCB' and 'stripline' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:00 |
| S19 | 320 | 'PCB' and 'stripline' and 'signal' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:28 |
| S20 | 1 | "6201194".PN. | USPAT; USOCR | OR | ON | 2005/01/12 11:03 |
| S21 | 1 | "6175087".PN. | USPAT; USOCR | OR | ON | 2005/01/12 11:04 |
| S22 | 1 | "6171946".PN. | USPAT; USOCR | OR | ON | 2005/01/12 11:06 |
| S23 | 1 | "6026564".PN. | USPAT; USOCR | OR | ON | 2005/01/12 11:07 |
| S24 | 245 | 'PCB' and 'stripline' and 'signal' and 'dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:10 |

| | | | | | | |
|-----|------|---|---|----|----|------------------|
| S25 | 20 | 'PCB' and 'stripline' and 'signal' and 'high dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:10 |
| S26 | 10 | 'Electromagnetic coupler circuit board' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:29 |
| S27 | 356 | 'Electromagnetic coupler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:31 |
| S28 | 217 | 'Electromagnetic coupler' and 'signal' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:40 |
| S29 | 38 | 'Electromagnetic coupler' and 'signal line' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:43 |
| S30 | 102 | 'Electromagnetic' with 'coupling' and 'signal trace' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 11:58 |
| S31 | 4915 | 'Electromagnetic' with 'coupling' and 'dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:02 |
| S32 | 497 | 'Electromagnetic' with 'coupling' and 'high dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:03 |
| S33 | 20 | 'PCB' and 'Electromagnetic' with 'coupling' and 'high dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:03 |
| S34 | 1685 | @ad<="20031022" and (257/734-736).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:07 |
| S35 | 1483 | @ad<="20031022" and (257/700).ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:07 |

| | | | | | | |
|-----|------|--|---|----|-----|------------------|
| S36 | 1105 | @ad<="20031022" and (257/750). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 13:34 |
| S37 | 879 | @ad<="20031022" and (257/762). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:08 |
| S38 | 648 | @ad<="20031022" and (257/211). ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 12:08 |
| S39 | 2 | ("0691193").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/12 12:17 |
| S40 | 2 | ("6449308").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/12 13:07 |
| S41 | 7 | ((("3615951") or ("6705895")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/01/12 13:07 |
| S42 | 27 | @ad<="20031022" and 'PCB' same 'FR4' same 'resin' same 'fiber' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 13:36 |
| S43 | 96 | @ad<="20031022" and 'FR4' with 'resin' with 'fiber' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/01/12 13:36 |
| S44 | 1 | "20050087877" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 14:33 |
| S45 | 30 | @ad<="20031022" and 'PCB' and 'copper' and 'epoxy' with 'fiber' and 'solder mask' and 'filler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 15:21 |

| | | | | | | |
|-----|-----|--|---|----|----|------------------|
| S46 | 1 | @ad<="20031022" and 'PCB' and 'copper' and 'epoxy' with 'fiber' and 'solder mask' and 'filler' with 'polyvinylidene' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 14:42 |
| S47 | 19 | @ad<="20031022" and 'copper' same 'filler' with 'polyvinylidene' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:24 |
| S48 | 0 | @ad<="20031022" and 'copper' same 'filler' with 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:25 |
| S49 | 0 | @ad<="20031022" and 'coper' same 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 14:44 |
| S50 | 0 | @ad<="20031022" and 'coper' and 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 14:44 |
| S51 | 0 | @ad<="20031022" and 'PCB' and 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 14:44 |
| S52 | 107 | @ad<="20031022" and 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 14:47 |
| S53 | 21 | @ad<="20031022" and 'dielectric' and 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 11:04 |
| S54 | 69 | @ad<="20031022" and 'FR4' and 'copper' with 'solder mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/28 15:21 |
| S55 | 25 | @ad<="20031022" and 'circuit board' and 'trace' with 'high dielectric' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 09:15 |
| S56 | 1 | "4967314".PN. | USPAT; USOCR | OR | ON | 2005/04/29 08:17 |
| S57 | 2 | @ad<="20031022" and 'trace' with 'high dielectric' same 'solder' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 09:15 |

| | | | | | | |
|-----|-----|--|---|----|----|------------------|
| S58 | 150 | @ad<="20031022" and 'PCB' and 'signal trace' and 'mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 09:39 |
| S59 | 11 | @ad<="20031022" and 'PCB' and 'signal trace' with 'mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 10:18 |
| S60 | 71 | @ad<="20031022" and 'PCB' and 'copper' with 'trace' with 'mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 09:48 |
| S62 | 0 | @ad<="20031022" and 'PCB' and 'copper' with 'trace' with 'mask' and 'high k' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 09:48 |
| S63 | 4 | Han-Dong-Ho.in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 10:18 |
| S64 | 18 | @ad<="20031022" and 'trace' with ('polyvinylidene diflouride' or pvdf) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 11:09 |
| S65 | 338 | @ad<="20031022" and 'copper' with ('polyvinylidene diflouride' or pvdf) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:57 |
| S66 | 0 | @ad<="20031022" and 'solder mask' same 'copper' with ('polyvinylidene diflouride' or pvdf) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 11:10 |
| S67 | 5 | @ad<="20031022" and 'PCB' and 'copper' with ('polyvinylidene diflouride' or pvdf) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 11:17 |
| S68 | 0 | @ad<="20031022" and 'PCB' and 'copper' and 'filler' with ('polyvinylidene diflouride' or pvdf) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 11:17 |
| S69 | 153 | @ad<="20031022" and 'filler' with ('polyvinylidene diflouride' or pvdf) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 11:17 |

| | | | | | | |
|-----|-----|---|---|----|-----|------------------|
| S70 | 0 | @ad<="20031022" and 'copper' same 'file' with ('polyvinylidene diflouride' or pvdf) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/04/29 11:18 |
| S71 | 321 | @ad<="20031022" and 'PCB' same 'filler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:02 |
| S72 | 49 | @ad<="20031022" and 'PCB' same 'filler' and 'mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 14:53 |
| S73 | 1 | "4361634".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:25 |
| S74 | 1 | "5150088".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:27 |
| S75 | 1 | "5185502".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:28 |
| S76 | 1 | "5185502".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:30 |
| S77 | 1 | "5278524".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:31 |
| S78 | 1 | "5278524".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:32 |
| S79 | 1 | "5677515".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:32 |
| S80 | 1 | "5719750".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:33 |
| S81 | 1 | "6072690".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:33 |
| S82 | 1 | "4567542".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:33 |
| S83 | 1 | "5400210".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:39 |
| S84 | 1 | "5378662".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:39 |
| S85 | 1 | "5371403".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:39 |
| S86 | 1 | "5177670".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:39 |
| S87 | 1 | "5027253".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:43 |
| S88 | 1 | "4999520".PN. | USPAT; USOCR | OR | ON | 2005/07/01 14:43 |
| S89 | 2 | ("5133120").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/01 14:54 |

| | | | | | | |
|------|-----|---|---|----|-----|------------------|
| S90 | 0 | @ad<="20031022" and 'photo solder resist' with 'dielectric constant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:03 |
| S91 | 0 | @ad<="20031022" and 'dielecric constant' with 'photo solder resist' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:03 |
| S92 | 19 | @ad<="20031022" and 'solder resist' with 'dielectric constant' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:10 |
| S93 | 0 | @ad<="20031022" and 'dielecric constant' with 'solder resist' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:03 |
| S94 | 1 | @ad<="20031022" and 'impedance' same 'insulative' and 'solder resist' and 'PCB' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:14 |
| S95 | 70 | @ad<="20031022" and 'impedance' same 'insulative' and 'PCB' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:17 |
| S96 | 43 | @ad<="20031022" and 'MULTILAYER PRINTED WIRING BOARD' same 'impedance' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:18 |
| S97 | 157 | @ad<="20031022" and 'MULTILAYER PRINTED WIRING BOARD' same 'filler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:45 |
| S98 | 4 | @ad<="20031022" and 'MULTILAYER PRINTED WIRING BOARD' same 'filler' and 'solder mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/01 15:18 |
| S99 | 7 | @ad<="20031022" and 'PRINTED WIRING BOARD' same 'dielectric filler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 06:35 |
| S100 | 2 | ('5162997').PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/04 06:30 |

| | | | | | | |
|----------|-----|---|---|----|-----|------------------|
| S10 1 | 1 | "4306273".PN. | USPAT; USOCR | OR | ON | 2005/07/04 06:32 |
| S10 2 | 3 | @ad<="20031022" and 'wiring board' and 'trace' with 'permittivity' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 06:39 |
| S10 3 | 554 | @ad<="20031022" and 'wiring board' same 'capacitance' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 06:40 |
| S10 4 | 3 | @ad<="20031022" and 'wiring board' same 'capacitance' and 'solder mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 06:47 |
| S10 5 | 17 | @ad<="20031022" and 'PCB' same 'capacitance' and 'solder mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 06:47 |
| S10 6 | 17 | @ad<="20031022" and 'PCB' same 'discrete' same 'signal path' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:01 |
| S10 7 | 26 | @ad<="20031022" and 'PCB' and 'trace' with 'filler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:27 |
| S10 8 | 4 | (("5162144") or ("5260170")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/04 07:12 |
| S10 9 | 1 | "4590115".PN. | USPAT; USOCR | OR | ON | 2005/07/04 07:19 |
| S11 0 | 1 | "4565606".PN. | USPAT; USOCR | OR | ON | 2005/07/04 07:19 |
| S11 1 | 91 | @ad<="20031022" and 'FR-4' and 'discrete' same 'trace' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:28 |
| S11 2 | 75 | @ad<="20031022" and 'FR-4' and 'discrete' with 'trace' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:28 |

| | | | | | | |
|----------|-----|--|---|----|----|------------------|
| S11 3 | 75 | @ad<="20031022" and 'FR-4' and 'trace' with 'discrete' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:28 |
| S11 4 | 13 | @ad<="20031022" and 'FR-4' and 'discrete' with 'trace' and 'mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:42 |
| S11 5 | 13 | @ad<="20031022" and 'FR-4' and 'capacitance' and 'dielectric filler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:49 |
| S11 6 | 12 | @ad<="20031022" and 'PCB' and 'capacitance' and 'dielectric filler' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 07:49 |
| S11 8 | 641 | @ad<="20031022" and 'copper' with 'polyvinylidene' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:39 |
| S11 9 | 29 | @ad<="20031022" and 'copper' and 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:38 |
| S12 0 | 1 | @ad<="20031022" and 'lead titanate' same 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:33 |
| S12 1 | 2 | @ad<="20031022" and 'lead titanate' and 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:37 |
| S12 2 | 0 | @ad<="20031022" and 'dielectric constant' same 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:37 |
| S12 3 | 6 | @ad<="20031022" and 'dielectric' same 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:37 |
| S12 4 | 0 | @ad<="20031022" and 'copper' same 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:38 |

| | | | | | | |
|----------|------|---|---|----|----|------------------|
| S12 5 | 0 | @ad<="20031022" and 'conductor' same 'polyvinylidene diflouride' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/04 08:38 |
| S12 6 | 1 | @ad<="20031022" and 'copper' with 'polyvinylidene' and 'PCB' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 07:43 |
| S12 7 | 60 | @ad<="20031022" and 'embedded' with 'capacitor' same 'PCB' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:33 |
| S12 8 | 12 | @ad<="20031022" and 'embedded' with 'capacitor' same 'PCB' and 'mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 07:59 |
| S12 9 | 12 | @ad<="20031022" and 'embedded' with 'capacitor' and 'PCB' and 'solder mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:04 |
| S13 1 | 2568 | @ad<="20031022" and 'dielectric constant' with 'polyimide' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:48 |
| S13 2 | 5 | @ad<="20031022" and 'dielectric' and 'PDF' and 'PZT' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:49 |
| S13 3 | 263 | @ad<="20031022" and 'dielectric' and 'pvdf' and 'PZT' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:55 |
| S13 4 | 1 | @ad<="20031022" and 'dielectric' and 'pvdf' and 'PZT' and 'FR-4' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:49 |
| S13 5 | 9 | @ad<="20031022" and 'dielectric' and 'pvdf' and 'PZT' and 'PCB' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:51 |
| S13 6 | 1 | "5656834".PN. | USPAT; USOCR | OR | ON | 2005/07/05 08:52 |
| S13 7 | 1 | "5347258".PN. | USPAT; USOCR | OR | ON | 2005/07/05 08:52 |
| S13 8 | 1 | "5261153".PN. | USPAT; USOCR | OR | ON | 2005/07/05 08:53 |

| | | | | | | |
|----------|-----|---|---|----|-----|------------------|
| S13 9 | 1 | "5162977".PN. | USPAT; USOCR | OR | ON | 2005/07/05 08:53 |
| S14 0 | 37 | @ad<="20031022" and 'dielectric' same 'pvdf' same 'PZT' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:58 |
| S14 1 | 0 | @ad<="20031022" and 'dielectric' same 'pvdf' same 'PZT' and 'wiring board' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 08:58 |
| S14 2 | 4 | @ad<="20031022" and 'dielectric' same 'pvdf' same 'PZT' and 'printed circuit board' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/07/05 10:21 |
| S14 3 | 10 | (("6349456") or ("5079069") or ("5261153") or ("5800575") or ("6274224")).PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/07/05 09:33 |
| S14 5 | 72 | @ad<="20031022" and 'embedded capacitor' same 'printed circuit board' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/30 14:21 |
| S14 6 | 1 | "5656834".PN. | USPAT; USOCR | OR | ON | 2005/07/05 10:27 |
| S14 7 | 153 | @ad<="20031022" and 'capacitor' same 'printed circuit board' and 'solder mask' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/30 14:09 |
| S14 8 | 2 | ("6618238").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/30 14:09 |
| S14 9 | 1 | "6021050".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:11 |
| S15 0 | 1 | "6016598".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:11 |
| S15 1 | 1 | "5959256".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:11 |
| S15 2 | 1 | "5753358".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:12 |
| S15 3 | 1 | "5120590".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:15 |
| S15 4 | 1 | "5172304".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:15 |

| | | | | | | |
|----------|----|---|---|----|----|------------------|
| S15 5 | 73 | @ad<="20031022" and 'embedded capacitor' same 'printed circuit board' | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/30 15:36 |
| S15 6 | 1 | "5656834".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:30 |
| S15 7 | 1 | "5347258".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:30 |
| S15 8 | 1 | "5261153".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:30 |
| S15 9 | 1 | "5162977".PN. | USPAT; USOCR | OR | ON | 2005/09/30 14:30 |